

## 200mA, Ultra-low Noise LDO Regulator

### General Description

The LP3993 is designed for portable applications with demanding performance and space requirements. The LP3993 performance is optimized for high voltage systems to deliver ultra low noise and low quiescent current. Regulator ground current increases only slightly in dropout, further prolonging the input system life. The LP3993 also works with low-ESR ceramic capacitors, reducing the amount of board space necessary for power applications, critical in hand-held wireless devices. The other features include ultra low dropout voltage, high output accuracy, current limiting protection, and high ripple rejection ratio.

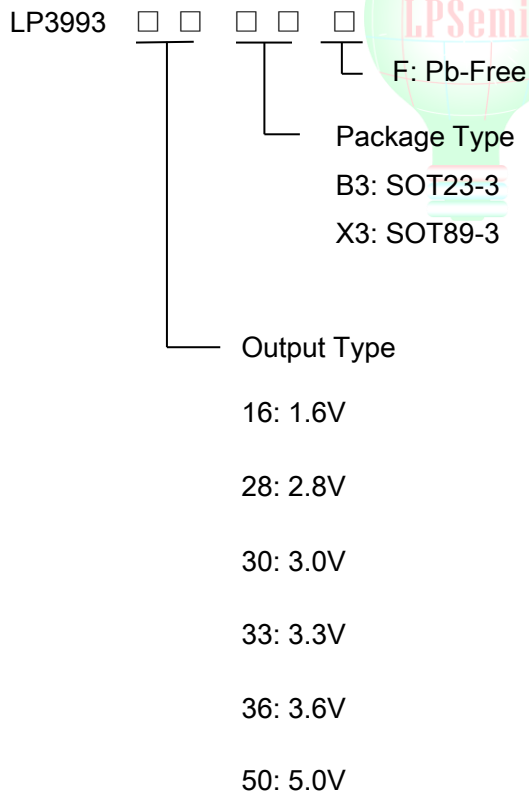
### Features

- ◆ Ultra-Low-Noise for RF Application
- ◆ High Input Voltage up to 28V
- ◆ Low Dropout Voltage
- ◆ Output Current 200mA
- ◆ Ultra-Fast Response in Line/Load Transient
- ◆ Fixed Output Voltages: 1.6V, 2.8V, 3.0V, 3.3V, 3.6V and 5.0V
- ◆ Current Limit and Thermal Shutdown Protection

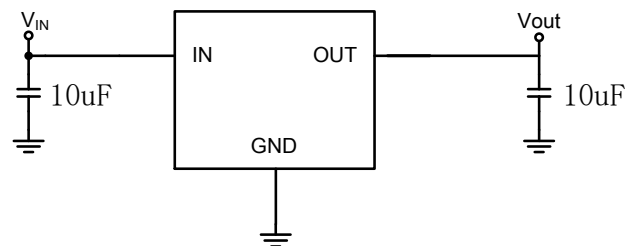
### Applications

- ◇ PMP/PDA/MP3 players
- ◇ Cellular and Mobile phone
- ◇ RF Module
- ◇ Sensor Module

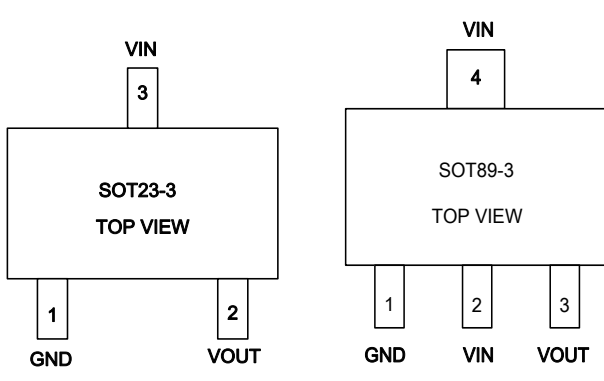
### Order Information



### Typical Application Circuit



## Functional Pin Description

Package Type	Pin Configurations
SOT-23-3 / SOT89-3	

## Pin Description

Pin		Name	Description
SOT23-3	SOT89-3		
1	1	GND	Ground.
3	2/4	IN	Power Input Pin
2	3	OUT	Output Pin.

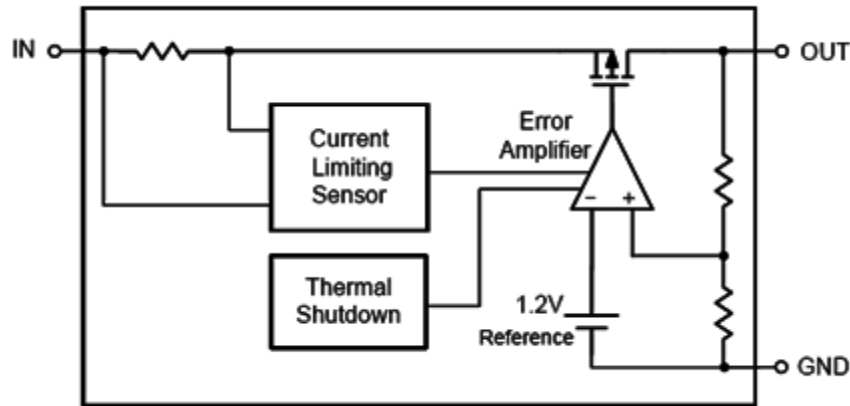
## Marking Information

Device	Marking	Package	Shipping	Device	Marking	Package	Shipping
LP3993-16B3F	LPS 20YWX	SOT23-3	3K/REEL	LP3993-33X3F	LPS 3993 33YW	SOT89-3	1K/REEL
LP3993-28X3F	LPS 3993 28YW	SOT89-3	1K/REEL	LP3993-36B3F	LPS 2LYW	SOT23-3	3K/REEL
LP3993-28B3F	LPS 2MYWX	SOT23-3	3K/REEL	LP3993-36X3F	LPS 36YWX	SOT89-3	1K/REEL
LP3993-30B3F	LPS 2NYWX	SOT23-3	3K/REEL	LP3993-50X3F	LPS 3993 50YW	SOT89-3	1K/REEL
LP3993-30X3F	LPS 3993 30YW	SOT89-3	1K/REEL	LP3993-50B3F	LPS 2KYWX	SOT23-3	3K/REEL
LP3993-33B3F	LPS 2EYWX	SOT23-3	3K/REEL				

Marking indication:

Y: Production year W: Production week X: Series Number

## Functional Diagram



## Absolute Maximum Ratings

- ◇ Supply Input Voltage ----- -0.3V to 32V
- ◇ Other pin to GND ----- -0.3V to 8V
- ◇ Maximum Junction Temperature ----- 150°C
- ◇ Maximum Soldering Temperature (at leads, 10 sec) ----- 260°C
- ◇ Operating Junction Temperature Range (T<sub>J</sub>) ----- -40°C to 150°C
- ◇ Storage Temperature ----- -50°C to 125°C

Power Dissipation, PD @ TA = 25°C

- ◇ SOT23-3 ----- 450mW
- ◇ SOT89-3 ----- 700mW

Package Thermal Resistance

- ◇ SOT23-3, θ<sub>JA</sub> ----- 250°C/W
- ◇ SOT89-3, θ<sub>JA</sub> ----- 165°C/W

ESD Susceptibility

- ◇ HBM (Human Body Model) ----- 2kV
- ◇ MM(Machine-Model) ----- 200V

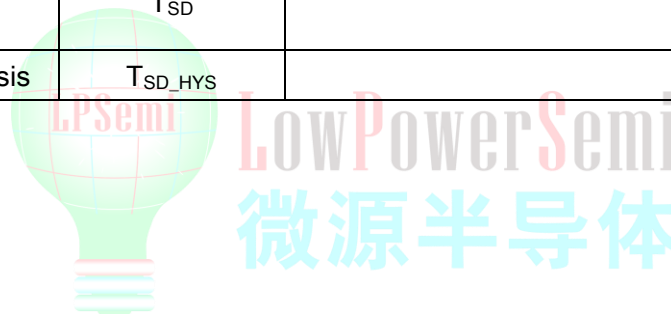
## Recommended Operating Conditions

- ◇ Supply Input Voltage ----- V<sub>OUT</sub>+1V to 28V

## Electrical Characteristics

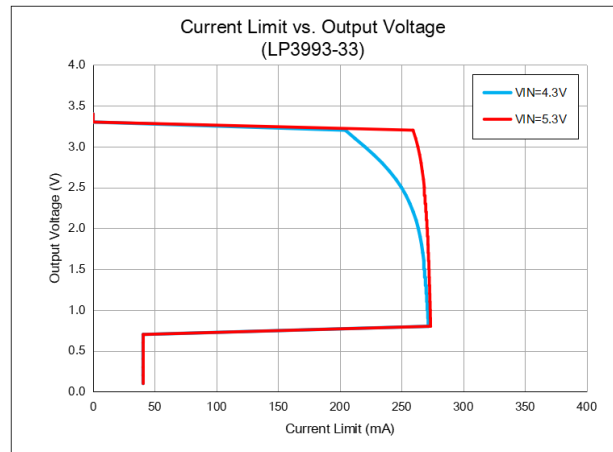
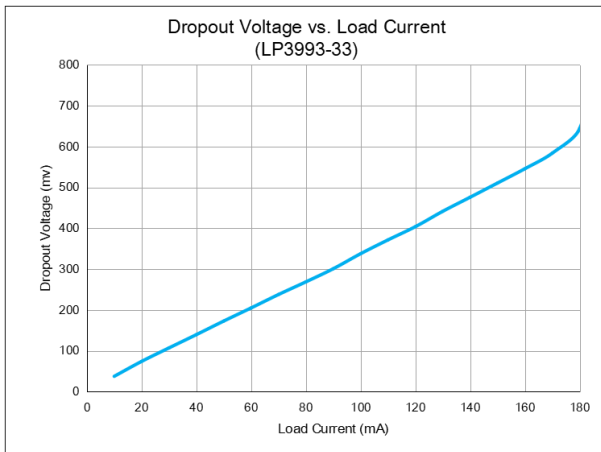
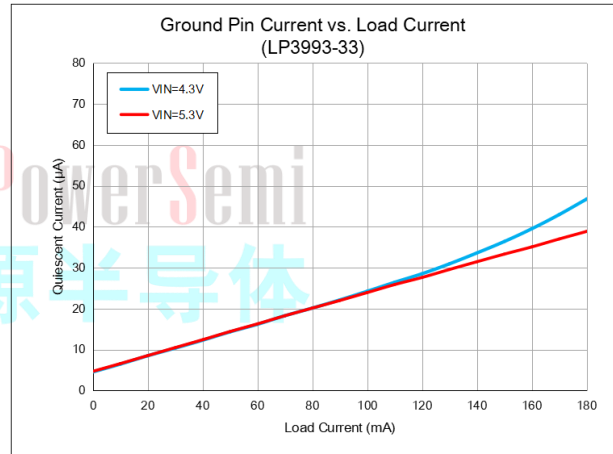
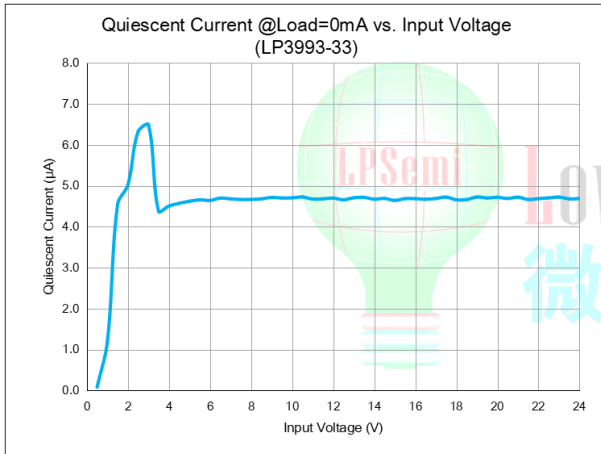
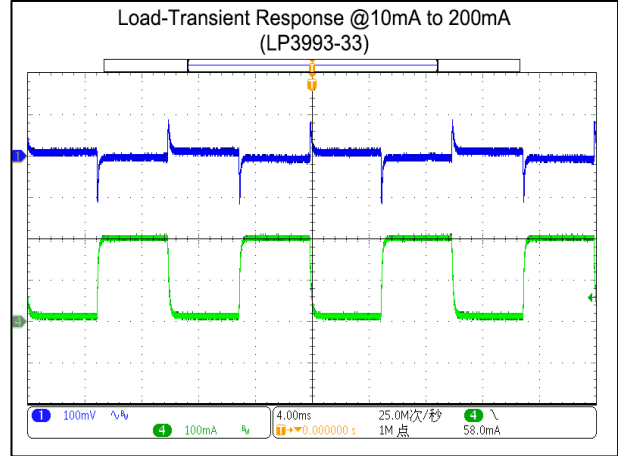
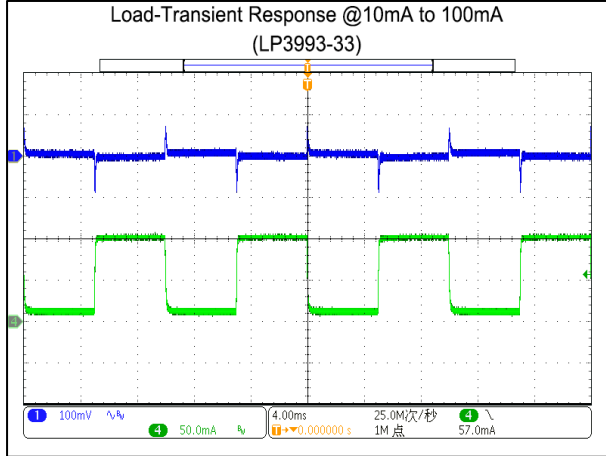
( $C_{IN} = 10\mu F$ ,  $C_{OUT} = 10\mu F$ ,  $V_{IN} = V_{OUT} + 1V$ ,  $T_a = 25^\circ C$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ.	Max	Units
Output Voltage Accuracy	$\Delta V_{OUT}$	$I_{OUT} = 1mA$	-1	--	+1	%
Output Loading Current	$I_{OUT}$			200		mA
Current Limit	$I_{LIM}$	$V_{OUT} = 0.9 * V_{OUT(nom)}$	250			
Quiescent Current	$I_Q$	No Load	2.5	4.5	6.5	$\mu A$
Dropout Voltage	$V_{DROP}$	$I_{OUT} = 100mA, V_{OUT} \geq 2.8V$	—	300	500	mV
		$I_{OUT} = 100mA, V_{OUT} < 2.8V$	—	480	600	mV
Linear Regulation	$\frac{\Delta V_{OUT}}{\Delta V_{IN} \times V_{OUT}}$	$V_{IN} = (V_{OUT} + 1V)$ to 12V, $I_{OUT} = 1mA.$	—	0.2	0.4	%
Load Regulation	$\frac{\Delta V_{OUT}}{V_{OUT}}$	$1mA < I_{OUT} < 150mA$			2	%
Thermal Shutdown Temperature	$T_{SD}$			150		$^\circ C$
Thermal Shutdown Hysteresis	$T_{SD\_HYS}$			25		$^\circ C$



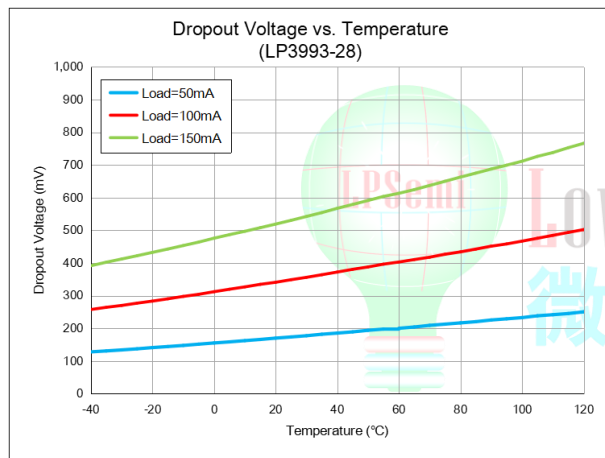
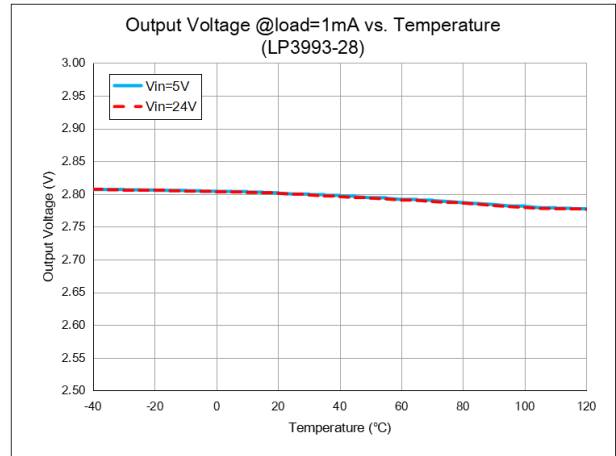
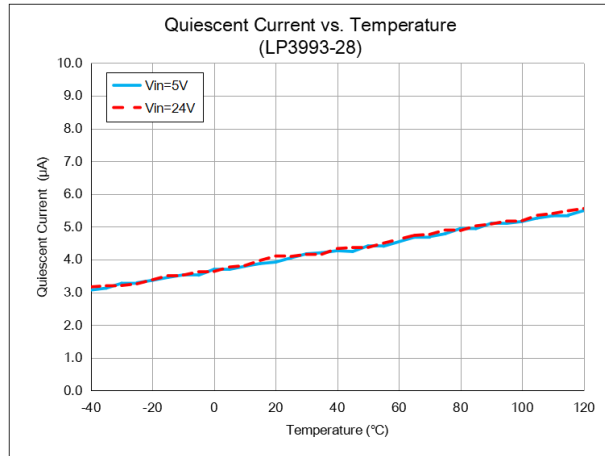
## Typical Performance Characteristics

( $C_{IN} = 10\mu F$ ,  $C_{OUT} = 10\mu F$ ,  $V_{IN} = V_{OUT} + 1V$ ,  $T_a = 25^\circ C$ , unless otherwise specified)



## Typical Performance Characteristics

( $C_{IN} = 10\mu F$ ,  $C_{OUT} = 10\mu F$ ,  $V_{IN} = V_{OUT} + 1V$ ,  $T_a = 25^\circ C$ , unless otherwise specified)



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## Applications Information

Like any low-dropout regulator, the external capacitors used with the LP3993 must be carefully selected for regulator stability and performance. Using a capacitor whose value is  $\geq 10\mu\text{F}$  on the LP3993 input. The input capacitor must be located a distance of not more than 0.5 inch from the input pin of the IC and returned to a clean analog ground. Any good quality ceramic or tantalum can be used for this capacitor. The capacitor with larger value and lower ESR (equivalent series resistance) provides better PSRR and line-transient response. The output capacitor must meet both requirements for minimum amount of capacitance and ESR in all LDO's application. The LP3993 is designed specifically to work with low ESR ceramic output capacitor in space-saving and performance consideration. Using a ceramic capacitor whose value is at least  $10\mu\text{F}$  with ESR is  $> 25\text{m}\Omega$  on the LP3993 output ensures stability. The LP3993 still works well with output capacitor of other types due to the wide stable ESR range. Output capacitor of larger capacitance can reduce noise and improve load transient response, stability, and PSRR. The output capacitor should be located not more than 0.5 inch from the  $V_{\text{OUT}}$  pin of the LP3993 and returned to a clean analog ground.

### Thermal Considerations

Thermal protection limits power dissipation in LP3993. When the operation junction temperature exceeds  $150^\circ\text{C}$ , the OTP circuit starts the thermal shutdown function turn the pass element off. The pass element turns on again after the junction temperature cools by  $25^\circ\text{C}$ .

The power dissipation definition in device is:

$$P_D = (V_{\text{IN}} - V_{\text{OUT}}) \times I_{\text{OUT}} + V_{\text{IN}} \times I_Q$$

The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate

of surroundings airflow and temperature difference between junction and ambient.

The maximum power dissipation can be calculated by following formula:

$$P_{D(\text{MAX})} = (T_{J(\text{MAX})} - T_A) / \theta_{JA}$$

Where  $T_{J(\text{MAX})}$  is the maximum operation junction temperature  $125^\circ\text{C}$ ,  $T_A$  is the ambient temperature and the  $\theta_{JA}$  is the junction to ambient thermal resistance. For recommended operating conditions specification of LP3993, the junction to ambient thermal resistance ( $\theta_{JA}$  is layout dependent) for LP3993 showed below.

SOT23-3 :  $250^\circ\text{C}/\text{W}$

SOT89-3 :  $165^\circ\text{C}/\text{W}$

And ,

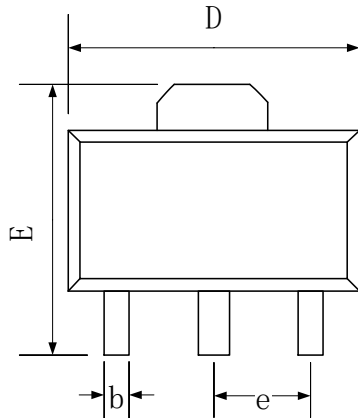
$$P_D = (125^\circ\text{C} - 25^\circ\text{C}) / 250^\circ\text{C}/\text{W} = 400\text{mW} \text{ (SOT23-3)}$$

$$P_D = (125^\circ\text{C} - 25^\circ\text{C}) / 165^\circ\text{C}/\text{W} = 600\text{mW} \text{ (SOT89-3)}$$

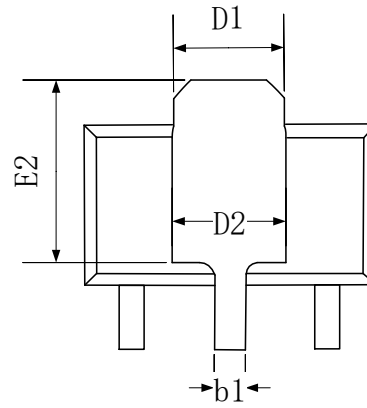
The maximum power dissipation depends on operating ambient temperature for fixed  $T_{J(\text{MAX})}$  and thermal resistance  $\theta_{JA}$ .

## Packaging Information

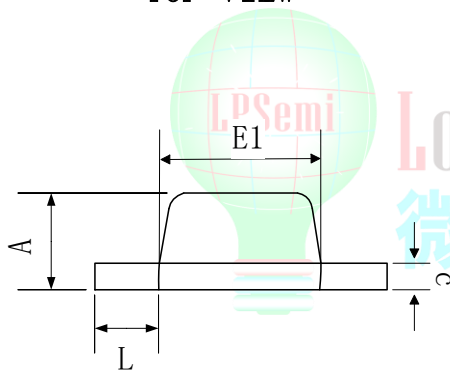
SOT-89



TOP VIEW



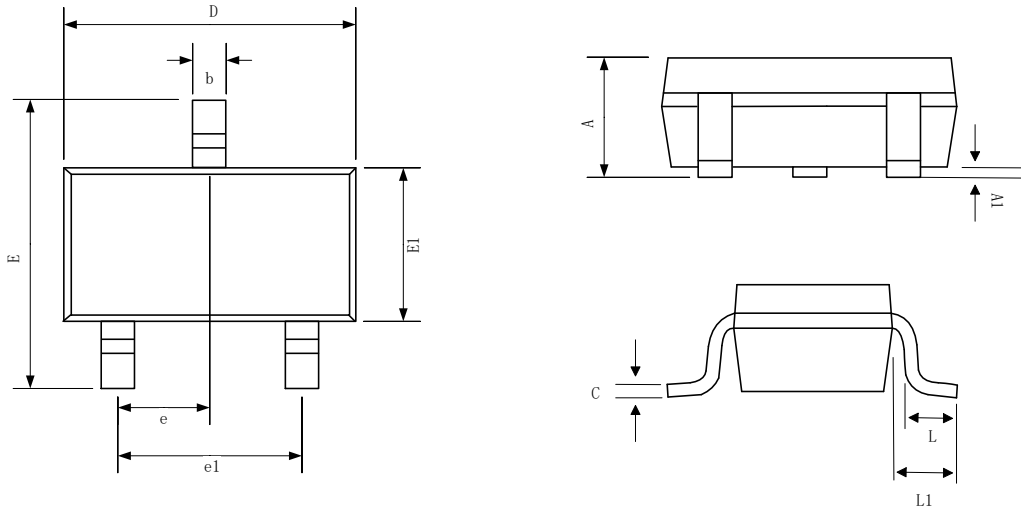
BOTTOM VIEW



SIDE VIEW

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	1.40	1.50	1.60
b	0.32	0.42	0.52
b1	0.36	0.48	0.56
c	0.35	-	0.44
D	4.39	4.50	4.60
D1	1.55 REF		
D2	1.63 REF		
E	3.9	4.20	4.40
E1	2.30	2.45	2.60
E2	2.75 REF		
e	1.50 BSC		
L	0.78	1.00	1.20

SOT23-3

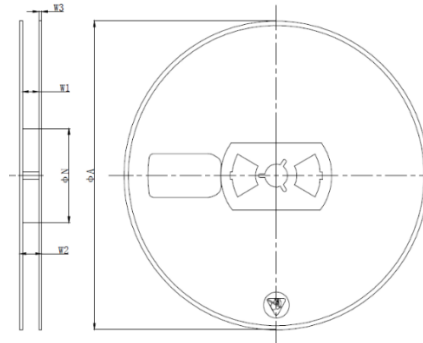


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	1.000	1.150	1.330
A1	0.000	0.050	0.130
b	0.300	0.380	0.450
c	0.110	0.150	0.190
D	2.820	2.920	3.020
E	2.600	2.800	3.000
E1	1.400	1.600	1.800
e	0.950BSC		
e1	1.900BSC		
L	0.300	0.450	0.600
L1	0.600REF		

## Tape and Reel Information

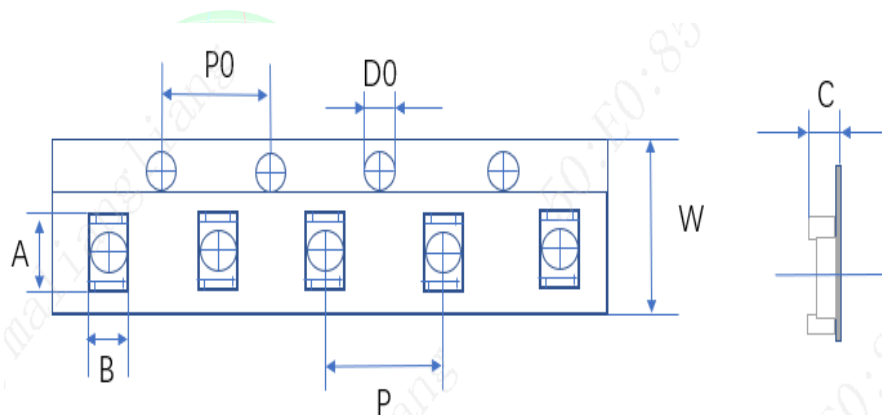
### SOT23-3

REEL DIMENSIONS (Unit:mm)



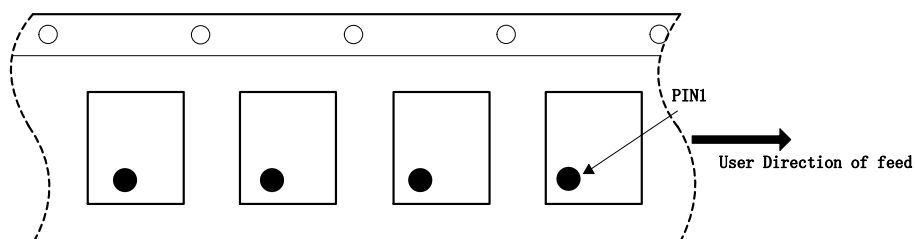
$\Phi A$	W2
$180 \pm 4$	$12 \pm 2$

TAPE DIMENSIONS (Unit:mm)



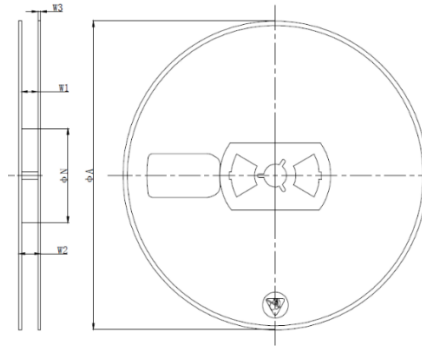
A	B	P0	P	D0	W	C
$3.20 \pm 0.50$	$3.15 \pm 0.50$	$4.00 \pm 0.20$	$4.00 \pm 0.20$	$1.50 \pm 0.20$	$8.00 \pm 0.30$	$1.3 \pm 0.40$

PIN1 AND TAPE FEEDING DIRECTION



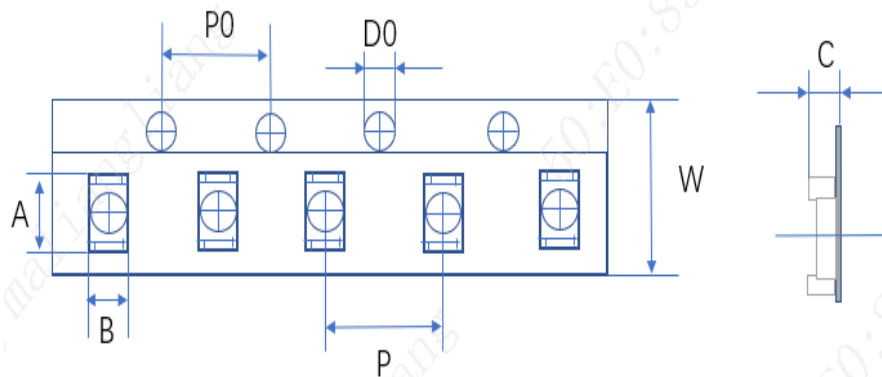
SOT-89

REEL DIMENSIONS (Unit:mm)



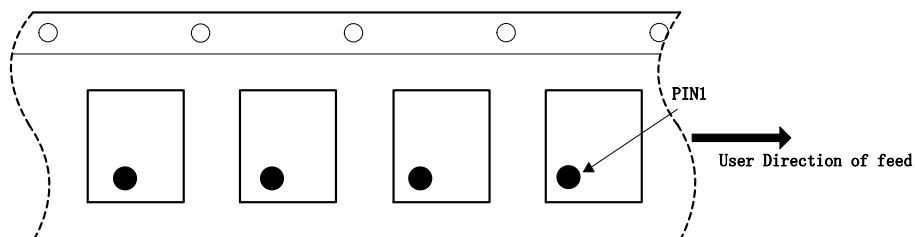
$\Phi A$	W2
$180 \pm 4$	$13 \pm 2$

TAPE DIMENSIONS (Unit:mm)



A	B	P0	P	D0	W	C
$4.43 \pm 0.20$	$4.80 \pm 0.20$	$4.00 \pm 0.20$	$8.00 \pm 0.20$	$1.50 \pm 0.20$	$12.00 \pm 0.30$	$1.85 \pm 0.20$

PIN1 AND TAPE FEEDING DIRECTION



## Classification of IR Reflow Profile

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/Soak		
Temperature Min( $T_{SMIN}$ )	100°C	150°C
Temperature Max( $T_{SMAX}$ )	150°C	200°C
Time( $T_s$ ) from ( $T_{SMIN}$ to $T_{SMAX}$ )	60~120 seconds	60~120 seconds
Ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max	3°C/second max
Liquidous temperature( $T_L$ )	183°C	217°C
Time( $t_L$ ) maintained above $T_L$	60~150 seconds	60~150 seconds
Peak package body temperature ( $T_P$ )	For users $T_P$ must not exceed the Classification temp in Table 1. For suppliers $T_P$ must equal or exceed the Classification temp in Table 1.	For users $T_P$ must not exceed the Classification temp in Table 2. For suppliers $T_P$ must equal or exceed the Classification temp in Table 2.
Time( $t_P$ )* within 5°C of the specified classification temperature( $T_C$ ), see Figure1	20* seconds	30* seconds
Ramp-down rate ( $T_P$ to $T_L$ )	6°C/second max	6°C/second max
Time 25°C to peak temperature	6 minutes max	8 minutes max
* Tolerance for peak profile temperature ( $T_P$ ) is defined as a supplier minimum and a user maximum.		

**Table 1 Sn-Pb Eutectic Process - Classification Temperatures (TC)**

Package Thickness	Volume mm3	
	<350	≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

**Table 2 Pb-Free Process - Classification Temperatures (TC)**

Package Thickness	Volume mm3		
	<350	350~2000	≥350
<1.6mm	260°C	260°C	260°C
1.6mm~2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

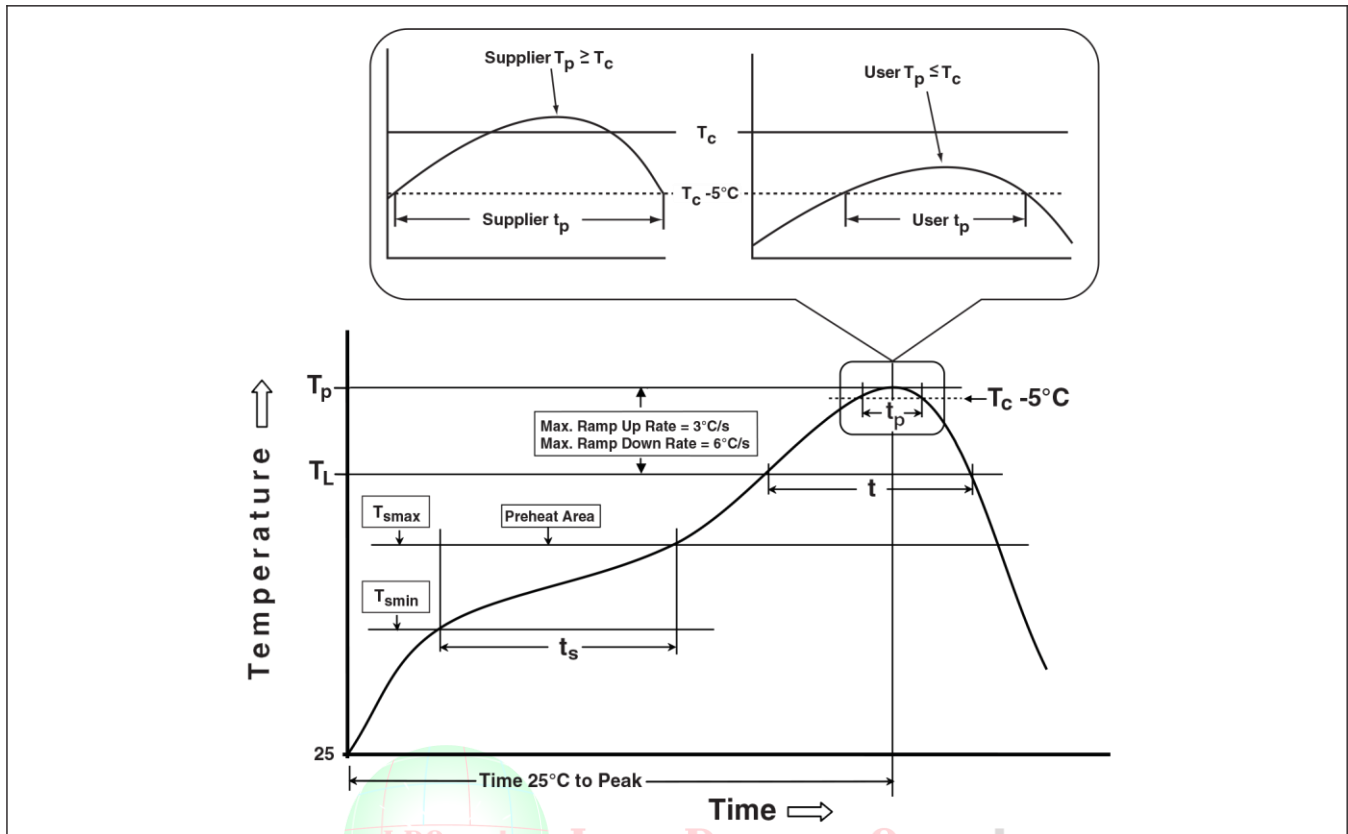


Figure1 Classification Profile (Not to scale)

Products Shipped Conform to “ROHS” Standards;

Moisture Sensitivity Level : MSL3 ( CONDITION :  $\leq 30\text{ }^{\circ}\text{C}/60\%\text{RH}$ , Time control:168 hours ) ;